

Global Fan Out Packaging Market 2022 - Industry Briefing

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Abstracts

According to market research study published by Gen Consulting Company, the market size of the global fan out packaging sector is expected to rise by USD 2.7 billion with a CAGR of 17.2% by the end of 2028.

This industry report offers market estimates of the global market, followed by a detailed analysis of the type, carrier type, business model, and region. The global market data on fan out packaging can be segmented by type: core-fan out, high-density fan out, ultra high-density fan out. Among these, the high-density fan out segment was accounted for the highest revenue generator in 2021. Fan out packaging market is further segmented by carrier type: 200 mm, 300 mm, Panel. The 300 mm segment is estimated to account for the largest share of the global fan out packaging market. Based on business model, the fan out packaging market is segmented into: foundry, integrated device manufacturer (IDM), outsourced semiconductor assembly and test (OSAT). The foundry segment held the largest share of the global fan out packaging market in 2021 and is anticipated to hold its share during the forecast period. On the basis of region, the fan out packaging market also can be divided into: China, Europe, Japan, South Korea, Taiwan, United States. In 2021, Taiwan made up the largest share of revenue generated by the fan out packaging market.

The global fan out packaging market is highly competitive. Key companies profiled in the report include Amkor Technology Inc., ASE Inc., JCET Group, Nepes Corporation, Powertech Technology Inc., Samsung Electronics Co. Ltd., Taiwan Semiconductor Manufacturing Company Limited.

The data-centric report focuses on market trends, status and outlook for segments. With comprehensive market assessment across the major geographies, the report is a



valuable asset for the existing players, new entrants and the future investors.

Why buy this report?

Get a detailed picture of the Global Fan Out Packaging Market

Identify segments/areas to invest in over the forecast period in the Global Fan Out Packaging Market

Understand the competitive environment, the market's leading players

The market estimate for ease of analysis across scenarios in Excel format.

Strategy consulting and research support for three months.

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Amkor Technology Inc. ASE, Inc. JCET Group Nepes Corporation Powertech Technology Inc. Samsung Electronics Co., Ltd. Taiwan Semiconductor Manufacturing Company Limited

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